

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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Property Type	Number
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14US037

转让证明
ASSIGNMENT

档案号 (限 12 个字符内): File reference: (12 characters maximum)	14US037
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鉴于壹圆人民币以及其他有益且充分的考虑, 本人特此将上述申请和在此申请中所公开的本发明创造, 以及要求此申请有关权利的任何接续申请或分案申请, 以及要求此申请优先权的任何外国申请的所有权益转让给

In consideration of One Chinese RMB and other good and sufficient consideration, I hereby assign my interest in the above-identified patent application and the invention disclosed therein, and any continuation or divisional application claiming the benefit therefrom, and any foreign patent application claiming priority therefrom,

to (1) THE HONG KONG POLYTECHNIC UNIVERSITY;
(2) TENCENT TECHNOLOGY (SHENZHEN) COMPANY LIMITED

其位于

having an address at

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(2) Room 403, East Block 2, SEG Park, Zhenxing Road, Futian, Shenzhen, Guangdong

本人授权代理人在得知本案申请号及申请日后将其填入上方。

I authorize the agent to insert the application number and filing date above when they are known.

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Inventor's signature

Luo XiaPu

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